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## **Supporting Information**

High-performance bio-based epoxies from ferulic acid and furfuryl alcohol:

## Synthesis and properties

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## Contents

Fig. S1 a) <sup>1</sup> H NMR, b) <sup>13</sup> C NMR and c) GC-MS spectra of GEFA.	.3
Fig. S2 Curing of FAE and DDS.	.3
Fig. S3 <sup>1</sup> H NMR spectra of a) P-FAE and b) after the reaction between P-FAE and GEFA	.4
Fig. S4 <sup>1</sup> H NMR spectra of the Diels-Alder adducts at 140 °C for 6 h and at 200 °C for 2 l	n.
	5
Fig. S5 FTIR spectra of the FAE <sub>1</sub> GEFA <sub>0</sub> system before and after curing.	.6
Fig. S6 Storage modulus as a function of temperature for the cured epoxy resins by DMA	. 6

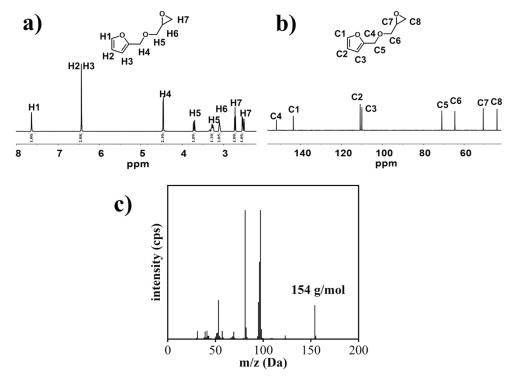


Fig. S1 a)  $^{1}$ H NMR, b)  $^{13}$ C NMR and c) GC-MS spectra of GEFA.

Fig. S2 Curing of FAE and DDS.

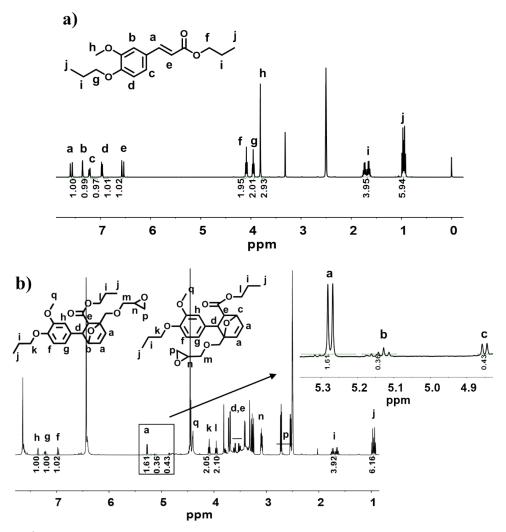


Fig. S3  $^1\text{H}$  NMR spectra of a) P-FAE and b) after the reaction between P-FAE and GEFA.

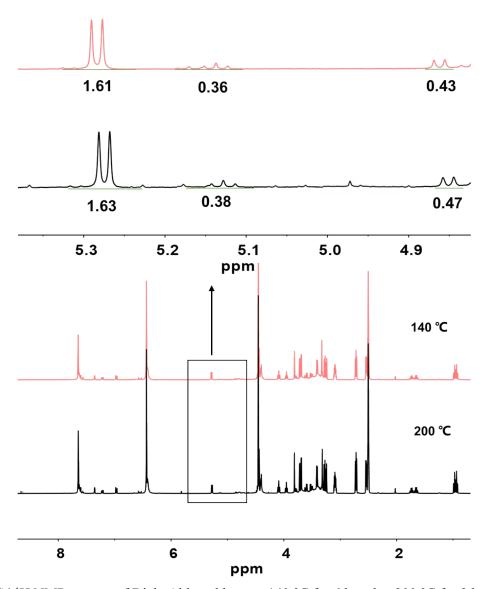


Fig. S4  $^1$ H NMR spectra of Diels-Alder adducts at 140  $^{\circ}$ C for 6 h and at 200  $^{\circ}$ C for 2 h.

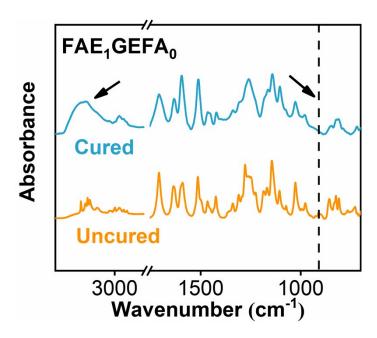


Fig. S5 FTIR spectra of the FAE<sub>1</sub>GEFA<sub>0</sub> system before and after curing.

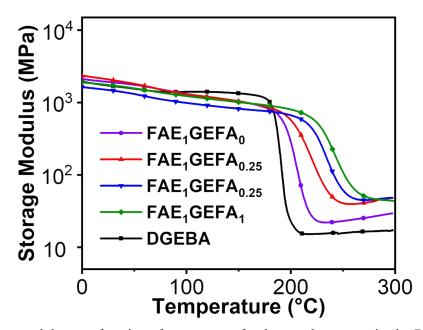


Fig. S6 Storage modulus as a function of temperature for the cured epoxy resins by DMA.